

OL-SA58671UK

Wafer level chip-size package; 16 balls; 2.06 x 2.11 x 0.6 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	17-10-2007

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		2.04	-	2.06	2.08	mm
E	package width		2.09	-	2.11	2.13	mm
A	seated height		[tbd]	-	[tbd]	0.64	mm
A ₂	package height		0.34	-	0.36	0.38	mm
e	nominal pitch		-	-	0.5	-	mm
n ₂	actual quantity of termination		-	-	16	-	



2. Package outline

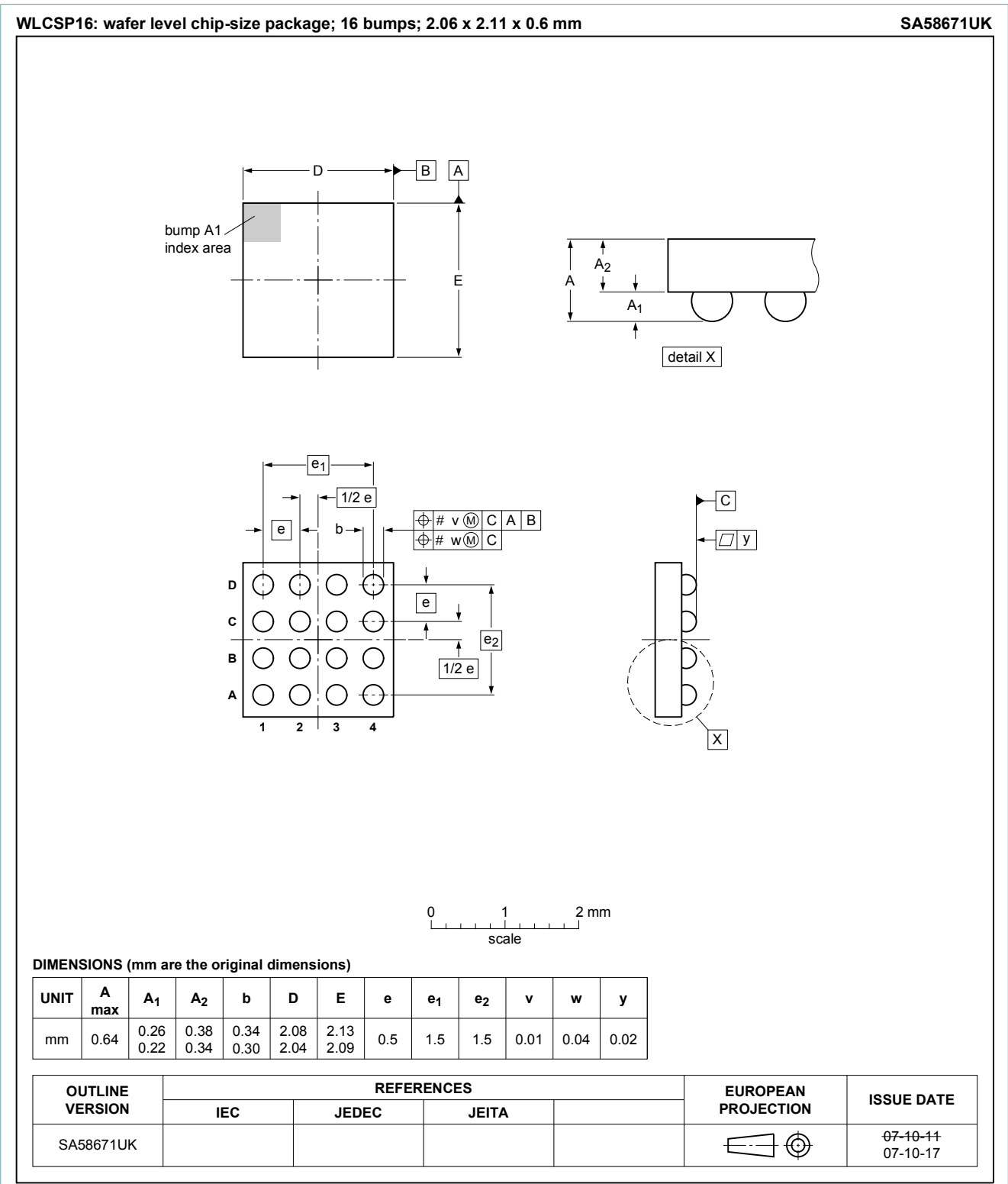


Fig. 1. Package outline WLCSP (OL-SA58671UK)

3. Legal information

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